

Inventor: Salman Akram et al.

Title: Methods of Sensing Temperature of an Electronic Device Workpiece

Assignee: Micron Technology, Inc.

**EL979949672**  
**INFORMATION DISCLOSURE STATEMENT**  
**PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98**

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a continuation application of co-pending application Serial No. 10/042,707, filed May 16, 2002, which is a continuation of U.S. Patent Application Serial No. 09/389,924, filed September 3, 1999, which was a divisional application of U.S. Patent Application Serial No. 09/032,184, filed February 27, 1998. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 2/6/04

By: 

James D. Shaurette  
Reg. No. 39,833

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-2469	SERIAL NO. Filed Herewith		
<b>LIST OF ART CITED BY APPLICANT</b> (Use several sheets if necessary)				APPLICANT Salman Akram et al.			
				FILING DATE Filed Herewith	GROUP Unknown		
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	4,560,216	12/24/1985	Egawa			
	AB	4,754,555	7/5/1988	Stillman			
	AC	5,475,317	12/12/1995	Smith			
	AD	5,325,052	6/28/1994	Yamashita			
	AE	5,495,667	3/5/1996	Farnworth et al.			
	AF	5,378,311	1/3/1995	Nagayama et al.			
	AG	5,886,863	3/23/1999	Nagasaki et al.			
	AH	5,141,334	8/25/92	Castles			
	AI	5,406,109	4/11/95	Whitney			
	AJ	5,435,646	7/25/95	McArthur et al.			
	AK	5,446,437	8/29/95	Bantien et al.			
	AL	5,612,574	3/18/97	Summerfelt et al.			
	AM	5,831,333	11/03/98	Malladi et al.			
	AN	5,492,011	2/20/1996	Amano et al.			
	AO	5,557,215	9/17/1996	Saeki et al.			
	AP	5,708,250	1/13/1998	Benjamin et al.			
	AQ	5,670,066	9/23/1997	Barnes et al.			
FOREIGN PATENT DOCUMENTS							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AR	Advertisement for Probe Technology from the Web Page of Interconnect Devices, Inc; 3/6/98, 1 page.					
	AS	Good Things Come In Small BGA/CSP Packages from Johnstech International, Corporation; Advertisement; 3/6/98 1 page.					
	AT	Product Description for Test Socket Contacts from the Web Page of Johnstech International, Corporation; <a href="http://www.johnstech.com">www.johnstech.com</a> ; 3/5/98; 1 page.					
EXAMINER				DATE CONSIDERED			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

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U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclasses	Filing Date If Appropriate
	AA	6,377,060 B1	4/23/2002	Burkhart et al.			
	AB	4,912,600	3/27/1990	Jaeger et al.			
	AC	5,436,494	7/25/1995	Moslehi			
	AD	5,969,639	10/19/1999	Lauf et al.			
	AE	4,335,463	10/26/1982	Burns			
	AF	3,710,251	1/9/1973	Hagge et al.			
	AG	6,020,750	2/1/2000	Berger et al.			
	AH	6,004,471	12/21/1999	Chuang			
	AI	5,550,526	8/27/1996	Mottahed			
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		Document Number	Date	Country	Class	Subclasses	Translation Yes      No
	AJ						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AK	Product Description for Double Ended Probes, B1052 Series, from the Web Page of Rika Denshi America, Inc.; <a href="http://www.testprobe.com">www.testprobe.com</a> ; 2/4/98, 1 page.					
	AL	Product Description for Test Centers, RM-500 Series Probes, from the Web Page of Rika Denshi America, Inc.; <a href="http://www.testprobes.com">www.testprobes.com</a> ; 2/4/98 1 page.					
	AM	Product Description for Cost Effective Interconnections for High I/O Products from the Web Page of Rika Denshi America, Inc.; <a href="http://www.testprobe.com">www.testprobe.com</a> ; 2/4/98 1 page.					
	AN	Product Description for Thermistors from Web Page of Therm-O-Disc, Inc., 2 pages.					
	AO	Product Description for RTD Sensors from Web Page of MTI Industrial Sensors, 3 pages.					
	AP	<i>Temperature Metrology for CD Control in DUV Lithography</i> , Jeffrey Parker and Wayne Renken, pp. 111-112, 114, 116, 09/17/97.					
	AQ	Product Description for RTD Modules from Web Page of Dataq Instruments, 2 pages.					
	AR	Product Description for RTD from Web Page of Minco Products Inc., 1 page (1996).					
	AS	Product Description for Ball Grid Probe B1303-C3 from the Web Page of Rika Denshi America, Inc.; <a href="http://www.testporbe.com">www.testporbe.com</a> ; 2/4/98 1 page					
	AT	P. Van Zant; "Microchip Fabrication;" (4th ed. 2000); pps 567-569.					
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*Examiner Initial		Document Number	Date	Name	Class	Subclas s	Filing Date If Appropriate
	AA	4,703,555	11/3/1997	Hubner			
	AB	5,347,869	9/20/94	Shie et al.			
	AC	5,719,333	2/17/98	Hosoi et al.			
	AD	5,919,548	7/6/99	Barron et al.			
	AE	5,492,011	2/20/96	Amano et al.			
	AF	5,551,283	9/3/96	Manaka et al.			
	AG	3,440,407	4/22/69	Golstos et al.			
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	AJ	4,332,081	6/1/82	Francis			
	AK	4,518,944	5/21/85	Faris			
<b>FOREIGN PATENT DOCUMENTS</b>							
		Document Number	Date	Country	Class	Subclas s	Translation Yes      No
	AL	2336778	7/1977	France			
	AM	56-12521	2/1981	Japan			
	AN	2-268462	11/1990	Japan			
	AO						
	AP						
<b>OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)</b>							
	AR		"Silicon Processing for the VLSI Era", Vol. 1: Process Technology, 2 <sup>nd</sup> Edition, Stanley Wolf, Ph.D. & Richard N. Tauber Ph.D., Lattice Press				
			2000, pgs. 22-34.				
	AS		Application Guide Temperature Sensors, Watlow Electrical Manufacturing Company Catalog, pp. 775-778, 1992/1993.				
	AT		In-Situ survey System of Resistive and Thermoelectric Properties of Either Pure or Mixed Materials in Thin Films Evaporated				
			Under Ultra High Vacuum, Lechevallier, LeHuerou, Richon, Sarrau, & Gouault, J. Phys. III France, Vol. 5, pp. 409-418, 04/95 (Abstract only).				
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